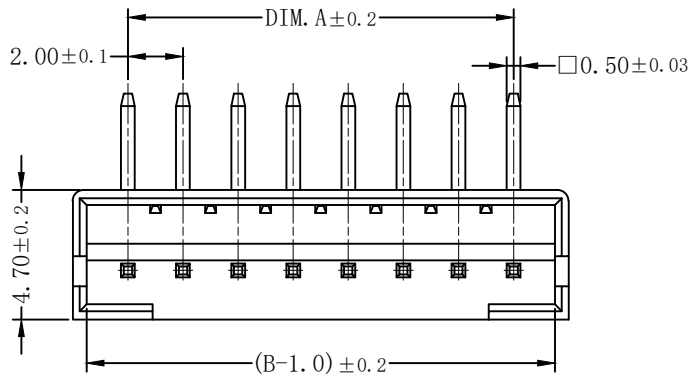
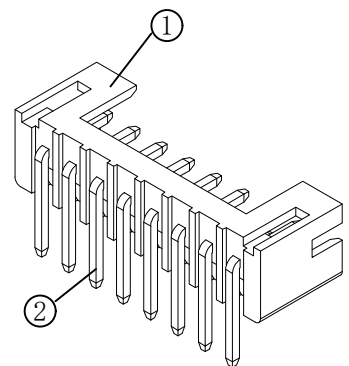
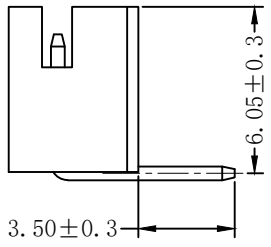
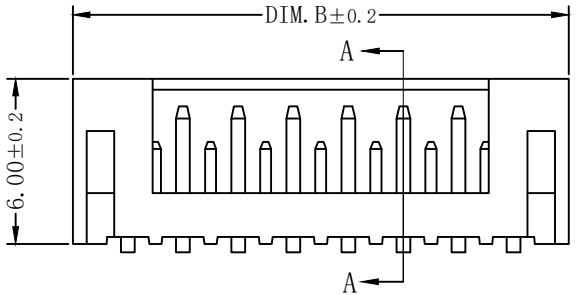


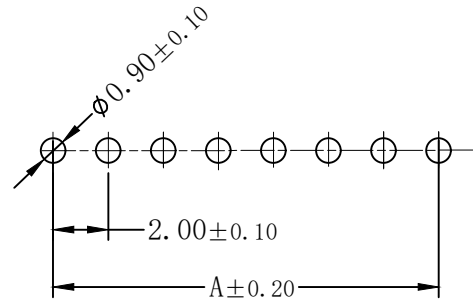
| REV. | DESCRIPTION | DATE |
|------|-------------|--------|
| A/0 | 新版发行 | 230509 |
| | | |
| | | |



- 技术要求:
- 1、塑件材料: PA66 (UL-94V-0)
 - 2、接触件: 黄铜镀锡
 - 3、接触电阻: $\leq 10m\Omega$
 - 4、绝缘电阻: $\geq 1000M\Omega$
 - 5、额定电压: 250V AC DC
 - 6、额定电流: 2.0A AC DC
 - 7、耐压: 能承受1000V AC/Minute
 - 8、工作温度: $-25^{\circ} \sim +85^{\circ}$
 - 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 235^{+5}_{-0} , 时间 2.5 ± 0.5 秒
 - 10、铅和镉等六大有害物质含量要符合环保要求



| Circuits | Dimensions (mm) | |
|----------|-----------------|-------|
| | A | B |
| 02 | 2.00 | 6.00 |
| 03 | 4.00 | 8.00 |
| 04 | 6.00 | 10.00 |
| 05 | 8.00 | 12.00 |
| 06 | 10.00 | 14.00 |
| 07 | 12.00 | 16.00 |
| 08 | 14.00 | 18.00 |
| 09 | 16.00 | 20.00 |
| 10 | 18.00 | 22.00 |
| 11 | 20.00 | 24.00 |
| 12 | 22.00 | 26.00 |
| 13 | 24.00 | 28.00 |
| ... | ... | ... |
| 20 | 38.00 | 44.00 |



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

| 序号 | 名称 | 材料 | 数量 | 附注 |
|----|------------|---------------|-------|---------------------------------|
| 2 | 端子 Contact | 黄铜 | n x 1 | 电镀层: 整个表面镀镍30u*MIN, 锡层 80u*MIN. |
| 1 | 基板 Wafer | PA66(UL94V-0) | 1 | 白色 |

| GENERAL TOLERANCES | | | | DRAWN BY | | Bossie (博锡) | |
|--------------------|-------|-------|-------|-------------|--|---------------|---------------|
| 0.X | ±0.25 | X.* | ±3° | CHK. BY | | | |
| 0.XX | ±0.12 | | | APRV. BY | | | |
| 0.XXX | ±0.05 | X.X* | ±0.5° | DRAWING NO. | | SHEET | PROD. NAME |
| UNIT | SIZE | SCALE | | 1 OF 1 | | PART NO. | PH 2.0 弯针 n P |
| MM | A4 | 1:1 | | TITLE | | BX-PH2.0-nPWZ | |

借用登记

旧底图总号

底图总号

签字

日期